

Title (en)  
Solventless silicone composition.

Title (de)  
Lösemittelfreie Silikon-Zusammensetzung.

Title (fr)  
Composition de silicone sans solvant.

Publication  
**EP 0614959 A1 19940914 (EN)**

Application  
**EP 94301423 A 19940228**

Priority  
US 3073993 A 19930312

Abstract (en)  
A method is provided for making a heat curable organopolysiloxane composition, such as a pressure sensitive adhesive composition by blending a benzene soluble resinous copolymer in the form of a spray dried particulate, comprising triorganosiloxy units, such as trimethylsiloxy units, and SiO<sub>2</sub> units with a fluid network mixture of an alkenyl siloxane, a silicon hydride siloxane and a hydrosilylation catalyst.

IPC 1-7  
**C09J 7/02; C09J 183/04; C08L 83/04**

IPC 8 full level  
**C08L 83/04** (2006.01); **C08L 83/05** (2006.01); **C08L 83/07** (2006.01); **C09J 7/38** (2018.01); **C09J 183/00** (2006.01); **C09J 183/04** (2006.01);  
**C09J 183/05** (2006.01); **C09J 183/07** (2006.01)

CPC (source: EP US)  
**C08L 83/00** (2013.01 - EP US); **C08L 83/04** (2013.01 - EP US); **C09J 7/38** (2017.12 - EP US); **C09J 183/04** (2013.01 - EP US);  
**C08G 77/12** (2013.01 - EP US); **C08G 77/20** (2013.01 - EP US)

C-Set (source: EP US)  
1. **C08L 83/04 + C08L 83/00**  
2. **C09J 183/04 + C08L 83/00**

Citation (search report)  
• [Y] EP 0506372 A2 19920930 - GEN ELECTRIC [US]  
• [Y] EP 0393426 A2 19901024 - GEN ELECTRIC [US]  
• [Y] EP 0291939 A2 19881123 - WACKER CHEMIE GMBH [DE] & US 4935484 A 19900619 - WOLFGRUBER MATTHIAS [DE], et al  
• [X] DATABASE WPI Derwent World Patents Index; AN 92-102379

Cited by  
EP1398361A1; EP0767216A1; EP1255252A3; EP0835918A3; GB2301829A; GB2301829B; EP1652899A1; EP3211139A4; EP0752443A3;  
US5723521A; EP0727462A3; US7534659B2; WO2004007628A1; US6903898B2; US7196867B2; US7659003B2; US8057909B2

Designated contracting state (EPC)  
DE FR GB

DOCDB simple family (publication)  
**EP 0614959 A1 19940914; EP 0614959 B1 20030129**; DE 69432062 D1 20030306; DE 69432062 T2 20031120; JP 3604716 B2 20041222;  
JP H06322354 A 19941122; US 5357007 A 19941018

DOCDB simple family (application)  
**EP 94301423 A 19940228**; DE 69432062 T 19940228; JP 3898294 A 19940310; US 3073993 A 19930312